PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7563576

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SATOSHI TAKASHIMA	09/16/2022

RECEIVING PARTY DATA

Name:	SONY GROUP CORPORATION
Street Address:	1-7-1 KONAN, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075
L	
Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Name: Street Address:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION 4-14-1 ASAHICHO, ATSUGI-SHI
Street Address:	4-14-1 ASAHICHO, ATSUGI-SHI

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17910382

CORRESPONDENCE DATA

Fax Number: (571)376-6334

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5713766333

Email: anaquadocketing@XSensus.com

XSENSUS, LLP **Correspondent Name:**

Address Line 1: 100 DAINGERFIELD ROAD, SUITE 402

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	18867US01
NAME OF SUBMITTER:	CHI PARK
SIGNATURE:	/Chi Park/
DATE SIGNED:	09/28/2022

Total Attachments: 1

PATENT REEL: 061245 FRAME: 0425

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PATENT REEL: 061245 FRAME: 0426 Attorney Docket No.: Client Ref. No.: SYP332364US01

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

As the below named inventor, I hereby declare that: This declaration is directed to: The attached application, or I United States application or PCT international application number PCT/JP2021/005069 filed on 10 February 2021 The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS. Song Group Corporation, Song Semiconductor Solutions Corporation WHEREAS. Song Group Corporation, Song Semiconductor Solution Corporation WHEREAS. Song Group Corporation, Song Semiconductor Solution Corporation WHEREAS. Song Group Corporation, Song Semiconductor Solution Corporation Solution Corporation Solution (Science Solution) The corporation of Solution Sol	Title of Invention	SIGNAL PROCESSING DEVICE, SIGNAL PROCESSING METHOD, AND PARAMETER SEARCH METHOD	
The attached application or PCT international application number PCT/JP2021/005069 filted on 10 February 2021 The above-identified application was made or authorized to be made by me. Ibelieve that I am the original inventor or an original joint inventor of a claimed invention in the application. WHERLAS, Song Group Corporation. Song Semiconductor Solutions Corporation WHERLAS, Song Group Corporation. Song Semiconductor Solutions Corporation. Song Semiconductor Solution Solution Solutions and Solutions Solutions Solutions Solution So	As the below	named inventor, I hereby declare that:	
The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, Sony Group Corporation, Sony Semiconductor Solations Corporation WHEREAS, Sony Group Corporation, Sony Semiconductor Solations Corporation with offices at 1.7-1 KONAN, MINATO-KU, TOKYO, JAPAN; 4-14-1 Anniche, Atsugi-shi, Kanagawa, Japan respectively (hereinafter referred to as ASSIGNEE(S)), and desirous of acquiring all interest in, to and under said invention, and any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE(S), their successors, assigns, and legal representatives, the entire right, title and interest in acid invention, said application, including any divisions and continuations thereof, and in and to any and all I return Patient of the United States, and countries foreign extent, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States adheres, and to any other benefits accurage or to accure to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to ssues and Letters Patent to said ASSIGNEE(S), as assignee(s) of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of said ASSIGNEE(S) or their successors, assigns, and legal representatives may from time-to-time pre	The attached application or		
Believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, Sony Group Corporation, Sony Semiconductor Solutions Corporation WHEREAS, Sony Group Corporation, Sony Semiconductor Solutions Corporation "with offices at 1-7-1 KONAN, MINATO-KU, TOKYO, JAPAN; 4-14-1 Asahicho, Atsugi-shi, Kanngawa, Japan respectively (hereinafter referred to as ASSIGNEE(S)), and desirous of acquiring all interest in, to and under said invention, asid application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries; NOW THEREPORE, in consideration of the sum of One Dollar (\$1,00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE(S), their successors, assigns, and legal representatives, the entire right, title and interest in said invention, asid application, including any divisions and continuations thereof, and in and to any and all I etters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all I etters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all Pietry rights and/or convention rights under the International Convention for Patents or securing on the convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said ASSIGNEE(S) as assignee(s) of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of said ASSIGNEE(S) or their successors, assigns, and legal represen			
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18-t-6:T-6-6:1	LEGAL NAM	ME OF INVENTOR	
Signature: /Satoshi Takashima/	Inventor: S	ATOSHI TAKASHIMA Date: 16 / 09 / 2022	
	Signature:	Satoshi Takashima	

RECORDED: 09/28/2022